Controllable N-Doping of Graphene

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ABSTRACT Opening and tuning an energy gap in graphene are central to many electronic applications of graphene. Here we report N-doped graphene obtained by NH3 annealing after N+ ion irradiation of graphene samples. First, the evolution of the graphene microstructure was investigated following N+ ion irradiation at different fluences using Raman spectroscopy, showing that defects were introduced in plane after irradiation and then restored after annealing in N2 or in NH3. Auger electron spectroscopy (AES) of the graphene annealed in NH3 after irradiation showed N signal, however, no N signal was observed after annealing in N2. Last, the field-effect transistor (FET) was fabricated using N-doped graphene and monitored by the source–drain conductance and back-gate voltage (Gsd–Vg) curves in the measurement. The transport property changed compared to that of the FET made by intrinsic graphene, that is, the Dirac point position moved from positive Vg to negative Vg, indicating the transition of graphene from p-type to n-type after annealing in NH3. Our approach, which provides a physical mechanism for the introduction of defect and subsequent hetero dopant atoms into the graphene material in a controllable fashion, will be promising for producing graphene-based devices for multiple applications.

KEYWORDS Graphene, N-doping, NH3 annealing, ion irradiation, Raman spectroscopy, field-effect transistor

Graphene, a two-dimensional (2D) network of sp2-hybridized carbon atoms packed into hexagonal structure, is a basic building block for graphitic materials of all other dimensionalities. Since long-range π-conjugation in graphene yields extraordinary thermal,1 mechanical,2 and electrical properties,3,4 an enormous effort has been devoted to exploration of its many applications in nanoelectronics, materials science, condensed-matter physics, and low-dimensional physics.5 However, most electronic applications are handicapped by the absence of a bandgap in the intrinsic material.6,7 In the quest to opening and tuning an energy gap in graphene, various approaches have been developed to improve the semiconducting properties, exemplified by forming confined geometries of quantum dots,8 nanoribbons9,10 and nanomesh,11 or binding graphene to particular substrates.12–14 One of the most feasible methods to control the semiconducting properties of graphene is by doping, which is a process intentionally used to tailor the electrical properties of intrinsic semiconductors. The dopant atoms can modify the electronic band structure of graphene, and open up an energy gap between the valence and conduction bands. The semiconducting graphenes by substituting C atoms with B and N atoms were reported through chemical doping, such as chemical vapor deposition (CVD) and electrothermal reactions.15–17 Nevertheless each of the approaches has its own downside, for instance, realization of binding graphene to certain substrates is very difficult and controversial, the magnitude of a nanoribbon gap is hard to control as it critically depends on the atomic-scale edge of the ribbon, and multilayer-graphene is common in the CVD method.

Ion irradiation has been used for doping in graphite, carbon nanotube (CNT),18–20 but for graphene, only defect, surface charge and electronic structure after ion irradiation were investigated.21–25 As we know, pristine graphene has perfect honeycomb structure, and it is difficult to introduce hetero atoms into graphene and control the electrical properties of graphene. In this letter, controllable N-doping in graphene was realized by NH3 annealing after ion irradiation. In addition, to the best of our knowledge it is the first reported n-type graphene-based field-effect transistor (FET) fabricated at room temperature by this method.

Electrical characteristics of graphene are linked to the quality of the 2D crystal structure,24,25 therefore it is necessary to investigate the effect of irradiation and annealing on the microstructure of graphene for further understanding the fundamental physics of the process. As a powerful tool for monitoring the process of irradiation and characterizing the properties of graphene,21,26 Raman spectroscopy (with 514 nm excitation) was used as a main means for the analysis of graphene samples used in the experiment. Otherwise, Raman measurement is also nondestructive, fast, high-resolution, and gives the maximum structural and electronic information.24,27,28

Since it is more useful to get n-type graphene compared to the easily obtained p-type graphene by adsorbates,17 we chose N, the natural candidate because of its similar atomic size as that of C and of its electron donor character for N-doping in graphene. To achieve this goal, we carried out N+ ion irradiation at room temperature in the vacuum...
features in the 1000–3000 cm\(^{-1}\) region. For the pristine graphene, the D peak does not show, indicating the high quality of the crystal lattice. As graphene is exposed to N\(^+\)-ions, the D peak, a signature for disorder at \(\sim 1345\) cm\(^{-1}\), and the weak D’ band at \(\sim 1620\) cm\(^{-1}\) considered another Raman feature induced by defects appear, displaying the increase of defects with the increasing exposure doses. The intensity of 2D band at \(\sim 2675\) cm\(^{-1}\), corresponding to the overtone of the D band,\(^{21}\) decreases by increasing the fluence of ion irradiation, and the ratio of \(I_D/I_G\) shows a linear increase with the increasing dose as shown in Figure 1c (green). The evolution of the aforementioned Raman spectra of graphene indicates that the disorder increases with the increase of the N\(^+\)-ion irradiation fluence.

The diagram of the ratio of \(I_D/I_G\) relative to the irradiation dose is plotted in Figure 2d (black). The ratio of \(I_D/I_G\) increases with the increasing fluence, then drops after reaching the highest value. The highest value of the curve is taken as a boundary between the first and second stage of disorder. In the first stage, a proper quantification of the amount of defects in graphene has been given by the well-known Tuinstra–Koenig (TK)\(^{30}\) relation, \(L_a = (2.4 \times 10^{-10})\lambda^2(I_D/I_G)\). Here \(L_a\) is the size of in-plane crystallites formed by a certain number of carbon rings and \(\lambda\) is the laser excitation wavelength.\(^{21,24,26,30}\) It can be assumed that the higher the number of defects with the increasing irradiation fluence, the higher the D peak intensity, and the smaller \(L_a\). While in the second stage, the TK relation was broken down as \(I_D/I_G \propto (I_D/I_G)^a\).\(^{24}\) The above relations can be used to determine which stage the graphene is in.

With the increase of the irradiation fluences, the microscopic structural properties of graphene will undergo a very important sequence of regimes: graphene-nanocrystalline graphene-low sp\(^3\) amorphous graphene-high sp\(^3\) amorphous carbon. The above three-stage classification of disorder allows to simply assess all the Raman spectra of carbons.\(^{20,21,24,31}\) At the first two stages, annealing at an appropriate temperature is able to restore the primitive order mostly.\(^{20,31}\) Therefore, the careful choice of a maximal threshold fluence is needed for the sake of restoration of the graphene structure after annealing. Considering the downshift of G band with the increasing fluence, the graphene irradiated with fluences at \(1 \times 10^{14}\) cm\(^{-2}\) in our experiment would be located at the beginning of the second stage, thus, the formation of amorphous carbon was avoided.

The Raman spectra display that the intensity of the D peak induced by irradiation is significantly reduced by postannealing in N\(_2\) (see Figure S1 in Supporting Information), indicating the restoration of the damaged lattice, that is, the irradiated graphene with the sp\(^3\)-like bonds or other vacancy defects would be changed into sp\(^2\)-bonded graphene after postannealing in N\(_2\). When increasing the temperature, the ratio of \(I_D/I_G\) decreases. The change of the annealing time causes little change of the \(I_D/I_G\) ratio, showing that the annealing time in our experiment is not the main factor for

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**FIGURE 1.** (a) The optical image of the mechanical exfoliated single-layer pristine graphene on the 300 nm SiO\(_2\)/p\(^+\)Si substrate. (b) The AFM image recorded in the red square of (a) with the cross-section analysis. (c) Raman spectra for various fluences of N\(^+\)-ions implanted into the same graphene sample. (d) Summary of the ratio of \(I_D/I_G\) and \(I_D/I_D\) relative to the irradiation dose.

Then, the graphene was irradiated with 30 keV N\(^+\)-ions at five different fluences: \(2 \times 10^{12}\), \(1 \times 10^{13}\), \(2 \times 10^{13}\), \(5 \times 10^{13}\), \(1 \times 10^{14}\) cm\(^{-2}\), and the corresponding Raman spectra are plotted in Figure 1c. The spectra show three main
affecting the restoration of defects in the irradiated graphene, and the similar result was obtained for the graphite sample (see Table S1 in Supporting Information).20 The irradiated graphene still keeps stable when postannealing up to the tested 1100 °C. After optimizing the annealing time and temperature, the largest upshift, minimal full width at half maximum (fwhm) of G band, the lowest ratio of I_{2D}/I_{G}, and the minimal intensity ratio of I_D/I_G ∼ 0.32, representing the maximal extent of restoration of defects, are obtained at the experimental condition of 1100 °C for 30 s.

Auger electron spectroscopy (AES) is an invaluable technique for chemical analysis of nanostructured materials and thin films. The spectra of AES (PHI-700 scanning auger nanoprobe) for the surface elemental analysis show no N signal in graphene after irradiation and postannealing in N₂ (Figure 2a, red), indicating that the N atomic concentration is too low to be detected by AES, or there is no N element in graphene after annealing in N₂. Therefore, most of the defects introduced by irradiation would be vacancy defects.32 For N-doping of graphene, NH₃ annealing was performed at 1100 °C for 30 s after irradiation. AES result shows N signal locating at ∼400 eV (Figure 2a, green), confirming the N-doping of graphene.

To further prove the NH₃ effect on the N-doping, the graphite flakes annealed in N₂ and in NH₃ under the same conditions as that for graphene were also measured by AES (Figure 2b) for a control experiment. Same as the result of graphene, no N signal in the graphite flake after annealed in N₂, but the N signal is detected after annealing in NH₃, which indicates that the doping of the graphite is not introduced by the irradiated N⁺ ions which might exist either in the graphite or in the substrate at the irradiation fluence used in our experiment. In addition, we annealed the pristine graphene in NH₃ under the identical conditions with that for the irradiated graphene and no N signal was observed. Our result is consistent with the previous report that the physisorbed NH₃ could be removed from the graphene surface by pumping17 and NH₃ completely desorbed from the pristine CNTs above 140 K.33 It should be noted that the O and Si signals appearing in the graphene sample come from the SiO₂ on the substrate surface because the electron of AES can reach the substrate across the one-atom thick graphene and no O and Si signals are observed in the graphite sample treated under the same conditions as that for the graphene.

The N-doping was also characterized by X-ray photoelectron spectroscopy (XPS, ESCA Lab220I-XL) on the graphite flake. The representative full spectrum of XPS for graphite annealed in N₂ and in NH₃ after irradiation is shown in Figure 2c, and no obvious difference is observed. But, the XPS N 1s spectra are dramatically different as displayed in the inset; the sample annealed in NH₃ after irradiation shows distinguished N signal. In contrast, the N signal for the sample annealed in N₂ after irradiation is not observable. The above
result verifies the N-doping effect in NH₃ after irradiation, which is consistent with the AES data.

Considering strain and tension of the graphene structure caused by the recovery of defects after annealing in N₂, the bands of Raman spectra upshift (Figure 3). The D band shifts ~19 cm⁻¹, while G band shifts ~15 cm⁻¹, and 2D band shifts ~28 cm⁻¹ after N₂ annealing at 1100 °C for 30 s relative to that of pristine graphene. However, the vacancy defects of the irradiated graphene are repaired with N atoms after annealing in NH₃ since the C–N bond formation occur predominantly on the defect sites in the plane, where the C atoms are much more chemically reactive than that in the plane of the perfect graphene. According to the previous report, the C–N bond internuclear distance is 0.134 nm and for the next neighbor C–C bonds a distance of 0.138 nm. Both of these values are only a little shorter than the C–C graphene distance of 0.14 nm, therefore, a torsion of 0.3 degrees was formed around C–N bonds. It suggests that the structural tension and strain of graphene cause the more prominent spectra upshift of the graphene annealed in N₂ after irradiation compared to that of the irradiated graphene after annealing in NH₃. On the other hand, the mode at ~1620 cm⁻¹, termed as D’ denoting disorder, becomes more prominent after annealing in NH₃ than in N₂, which might be caused by hetero N atoms.

To investigate the electronic properties of different graphene samples, the graphene-based back-gate FETs were fabricated on a 300 nm SiO₂/p⁺Si substrate and the source/drain electrodes were defined by electron beam lithography and thermal metal deposition of Cr/Au (5 nm/70 nm) as shown by the scheme and SEM image in Figure 4a.

The source–drain conductance and back-gate voltage ($G_{sd}$–$V_g$) curves of the pristine graphene FET measured in air and in vacuum (Figure 4b) show bipolar transistor effect, and the minimal conduction corresponds to the Dirac point.
(\(V_{\text{dirac}}\)). When \(V_g < V_{\text{dirac}}\), it operates as a p-channel FET, and for \(V_g > V_{\text{dirac}}\), the device operates as an n-channel FET.\(^{30}\) Therefore, the \(V_{\text{dirac}}\) locating at the positive gate voltage indicates the p-type hole doping behavior of pristine graphene due to doping of the physisorbed molecular oxygen.\(^{15,18,30}\) For the graphene annealed in \(N_2\) after irradiation, it shows obvious p-type doping due to the defects and the physisorbed oxygen molecules,\(^{17}\) and the bipolar transistor effect disappeared (Figure 4c).

In our transport measurement, the graphene annealed in \(NH_3\) after irradiation shows distinguishing transport features both in vacuum and in air (Figure 4d) compared with the pristine graphene FET and the FET with the graphene annealed in \(N_2\). In vacuum, the graphene FET displays intrinsic clear n-type behavior with the Dirac point at the negative gate voltage, showing N-doping in graphene. Pumping in vacuum reduces the hole conduction and enhances the electron conduction, which corresponds to a decrease in p-type doping caused by partial physical adsorption. Because of the adsorption of oxygen molecule in air, the hole and electron conduction change at the different \(V_g\) and the minimal conduction locates at the positive \(V_g\).\(^ {17}\) (See more transport data in Figure S2 of Supporting Information). The carrier mobility (\(\mu\)) can be deduced by \(\mu = L/WC_g(V_{sd}/\Delta V_g)^{15}\) where \(C_g\) is the gate capacitance per unit area (ca. 7 nF cm\(^{-2}\)); \(L\) and \(W\), channel length and width, are about 2 and 5–10 \(\mu\)m, respectively; \(V_{sd}\) is 50 mV in our experiment. For the pristine graphene, the hole and electron mobilities are about 15 000 and 6700 cm\(^2\) V\(^{-1}\) s\(^{-1}\), respectively, which are consistent with the reported values.\(^7\) For our N-doped graphene, the hole and electron mobilities are about 6000 cm\(^2\) V\(^{-1}\) s\(^{-1}\), higher than the values reported by nanoribbon,\(^ {17}\) graphene oxide, and graphene produced by CVD\(^ {15}\) or arc discharge.\(^ {41}\) Note that the electronic property of graphene annealed in \(N_2\) after irradiation does not degrade, which is consistent with our previous conclusion that the defect of graphene could be restored after annealing in \(N_2\) and the formation of the amorphous structure in graphene samples was avoided at the maximum fluence used in our experiment.\(^ {21}\) However, the conductance of the graphene annealed in \(NH_3\) after irradiation is a few times lower compared to that of the pristine graphene, and it might be caused by the N atoms doping.

The atomic configuration and corresponding schematic band structures of the graphene illustrated in Figure 5 help to interpret the whole process of the experiment. The pristine graphene has 2D honeycomb atomic configuration and zero-gap band structure as shown in Figure 5a. After \(N^+\)-ion irradiation, the defects are induced as shown in Figure 5b. When annealing in \(NH_3\), the last step to realize the change of Fermi energy in graphene,\(^ {31,42}\) \(NH_3\) decomposes into atomic N, which can combine with the defect sites of the graphene as displayed by the right scheme in Figure 5c,\(^ {43}\) forming the most stable bonding against the high temperature based on the previous reports about the substitutional N-doping.\(^ {18–20,22,30}\)

After optimizing the fabrication process, for example, using shorter channel length, better contact metal, the device performances and doping efficiency will be greatly improved. The electronic properties of devices can also be exactly tuned by changing the doping parameters, such as dopant atoms, doping energy, and doses. The n-typed graphene together with the p-typed graphene can be used to fabricate p-n junction, which is the core of semiconductor devices, for example, junction transistor and integrated circuit. Our method provides a new approach for making N-doped graphene, which has promising prospect for producing graphene-based devices for multiple applications.

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Supporting Information Available. Additional figures of effect of \(N_2\) annealing on Raman spectra of graphene after irradiation and the transport data measured in vacuum for different graphene-based FETs are available free of charge via the Internet at http://pubs.acs.org.

REFERENCES AND NOTES

Supporting Information

Controllable N-Doping of Graphene

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Figure S1. Effect of N₂ annealing on Raman spectra of graphene after irradiation. The D, G and 2D bands of the irradiated graphene shift to higher frequency with the increase of the annealing temperature and time, respectively. The intensity of the D peak induced by irradiation is significantly reduced after post-annealing, indicating the restoration of the damaged lattice.
Table S1. Position and FWHM of G band and the ratio of $I_{2D}/I_G$ and $I_D/I_G$ in Figure S1 of Supporting Information.

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<th>$I_D/I_G$</th>
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<td>3.06</td>
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Figure S2. The transport data measured in vacuum for different graphene-based FETs. The different color of the $G_{sd}$-$V_g$ curves indicates different devices annealed in $N_2$ and in $NH_3$. The graphene was annealed (a) in $N_2$ and (b) in $NH_3$ after irradiation, and the variation of data is due to the difference of the device fabrication.